

**AMENDMENTS TO THE CLAIMS:**

Please amend claims 31, 32, 42 and 43, as shown below.

This listing of claims will replace all prior versions and listings of claims in the  
Application:

**Claims 1-30 (canceled)**

**Claim 31 (currently amended):** A semiconductor device comprising:

a first transistor which is connected between a first power supply line and a first node  
and has a gate that is connected to a second node without connection to a first node;

a second transistor which is connected between a second power supply line and said  
second node and has a gate that is connected to a first node without connection to said second  
node;

an extended gate wiring that is extended from the gate electrode of said first transistor  
up to the vicinity of a diffusion layer of said second transistor; and

a common contact formed across the extended gate wiring and the diffusion layer of  
said second transistor,

said transistor comprising:

a semiconductor substrate;

a gate insulation film formed on said semiconductor substrate;

a gate electrode formed on said gate insulation film and having a portion increasing  
upward in the length along a gate length direction, said gate electrode further having a visor  
portion; and

a side wall formed on a side surface of said gate electrode so as to be covered behind  
[[a]] said visor portion of said gate electrode[[;]],

~~an interlayer insulation film covering said gate electrode; and~~  
~~a contact formed in said interlayer insulation film and being in contact with a top~~  
~~surface and a side surface of said visor portion, said side wall and said diffusion layer a silicide~~  
~~film formed on a top surface of said semiconductor substrate;~~

wherein said visor portion has no overhang with respect to said side wall.

**Claim 32 (currently amended):** A semiconductor device comprising:

a first transistor which is connected between a first power supply line and a first node  
and has a gate that is connected to a second node without connection to a first node;

a second transistor which is connected between a second power supply line and said  
second node and has a gate that is connected to a first node without connection to said second  
node;

an extended gate wiring that is extended from the gate electrode of said first transistor  
up to the vicinity of a diffusion layer of said second transistor; and

a common contact formed across the extended gate wiring and the diffusion layer of  
said second transistor.

said transistor comprising:

a semiconductor substrate;

a gate insulation film formed on said semiconductor substrate;

a gate electrode formed on said gate insulation film and having a portion increasing  
upward in the length along a gate length direction, said gate electrode further having a visor  
portion; and

a side wall formed on a side surface of said gate electrode so as to be covered behind  
[[a]] said visor portion of said gate electrode, said side wall being formed of a lamination of at  
least two insulation films having different etching properties,

wherein said visor portion has no overhang with respect to said side wall.[:,] and

~~a contact formed in said interlayer insulation film and being in contact with a top  
surface and a side surface of said visor portion, said side wall and said diffusion layer a silicide  
film formed on a top surface of said semiconductor substrate.~~

**Claim 33 (canceled)**

**Claim 34 (previously presented):** The semiconductor device according to claim 31,  
wherein said gate electrode comprises a lower part substantially constant in the length along  
said gate length direction, and an upper part on said lower part increasing upward in the length  
along said gate length direction.

**Claim 35 (previously presented):** The semiconductor device according to claim 32,  
wherein said gate electrode comprises a lower part substantially constant in the length along  
said gate length direction, and an upper part on said lower part increasing upward in the length  
along said gate length direction.

**Claim 36 (canceled)**

**Claim 37 (previously presented):** The semiconductor device according to claim 34,  
wherein said side wall is formed on both a side surface of said upper part and a side surface of  
said lower part.

**Claim 38 (previously presented):** The semiconductor device according to claim 35,  
wherein said side wall is formed on both a side surface of said upper part and a side surface of  
said lower part.

**Claim 39 (canceled)**

**Claim 40 (previously presented):** The semiconductor device according to claim 37, wherein a side surface of said upper part forms a tapered slope.

**Claim 41 (previously presented):** The semiconductor device according to claim 38, wherein a side surface of said upper part forms a tapered slope.

**Claim 42 (currently amended):** The semiconductor device according to claim 31, wherein ~~said gate electrode is a gate electrode of one transistor and~~ said diffusion layer is also a diffusion layer of a drain or source of ~~another~~ a third transistor.

**Claim 43 (currently amended):** The semiconductor device according to claim 32, wherein ~~said gate electrode is a gate electrode of one transistor and~~ said diffusion layer is also a diffusion layer of a drain or source of ~~another~~ a third transistor.

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